Docket No.

239476US2

IN RE APPLICATION OF: Takeru MATSUOKA, et al.

SERIAL NO: 10/603,811

FILED:

June 26, 2003

FOR:

SEMICONDUCTOR DEVICE INCLUDING COPPER INTERCONNECT LINE AND BONDING PAD, AND

METHOD OF MANUFACTURING THE SAME

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

Transmitted herewith is an amendment under 37 C.F.R. §1.312 in the above-identified application.

- No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- Additional documents filed herewith:

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS		RATE		CALCULATIONS
TOTAL	12	MINUS	20	0	x	\$18	=	\$0.00
INDEPENDENT	5	MINUS	5	0	x	\$86	=	\$0.00
-		☐ MULTIPI	LE DEPENDENT	CLAIMS	+	\$290	-	\$0.00
		TOTAL OF ABOVE CALCULATIONS				\$0.00		
		☐ Reduction by 50% for filing by Small Entity						\$0.00
		☐ Recordation of Assignment + \$40 =				\$0.00		
						TO	ΓAL	\$0.00

	Α	A check in the amo	ount of \$0.00	is attached
--	---	--------------------	-----------------------	-------------

- ☐ Credit card payment form is attached to cover the fees in the amount of **§0.00**
- Please charge any additional Fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Eckhard H. Kuesters

Registration No. 28,870

Customer Number

22850

Tel. (703) 413-3000 Fax. (703) 413-2220 (OSMMN 05/03)

I:\USER\MDAVI\23s\239476\AME CV 312.DOC



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF : DATE ALLOWED: JULY 14, 2004

TAKERU MATSUOKA, ET AL. : EXAMINER: CLARK, S.

SERIAL NO: 10/603,811

: GROUP ART UNIT: 2815 FILED: JUNE 26, 2003

FOR: SEMICONDUCTOR DEVICE INCLUDING COPPER INTERCONNECT LINE AND BONDING PAD, AND METHOD OF MANUFACTURING THE

SAME

AMENDMENT UNDER 37 C.F.R. § 1.312

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Notice of Allowance and Fee(s) Due mailed July 14, 2004, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.